Material Composition

Product GS1572-IBE3
Package 100L LBGA
Manufacturer Gennum Corporation **Date** 02/27/2008

Component	BOM	Weight of Component mg	Substance	Weight of Substance mg	Homogeneous material %	ppm
Substrate	BT	159.84	SiO2	17.023	10.65	106500
			Acrylic	15.984	10.00	100000
			Epoxy	12.787	8.00	80000
			Bisphenol	23.976	15.00	150000
			Triazol	27.972	17.50	175000
			Cu	58.821	36.80	368000
			Ni	2.398	1.50	15000
			Au	0.879	0.55	5500
			Sub-total	159.840	100.00	1000000
Mold Compound	KE-G1250	159.24	Silica (fused)	140.131	88	880000
			Epoxy resin	9.554	6	60000
			Phenolic resin	8.758	5.5	55000
			Carbon black	0.796	0.5	5000
			Sub-total	159.240	100.00	1000000
Chip		11.30	Si	11.232	99.4	994000
			Al	0.068	0.6	6000
			Sub-total	11.300	100.00	1000000
Die Attach	Ablestik 2100A	5.11	Ag	3.935	77	770000
			Epoxy Resin	0.332	6.5	65000
			Functionalized Resin	0.332	6.5	65000
			Diester	0.511	10	100000
			Sub-total	5.110	100.00	1000000
Wire	25_NL03F	3.69	Au	3.690	99.99	999900
			impurities		0.01	100
			Sub-total			1000000
Marking Ink	Teca 460	0.15			100	1000000
Solder Balls	Senju	48.64	Sn	46.451	95.5	955000
			Ag	1.946	4	40000
			Cu	0.243	0.5	5000
			Sub-total	48.640	100.00	1000000
Total		387.97				

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